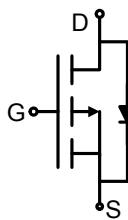


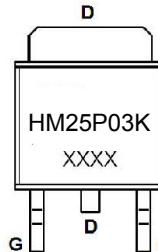
P-Channel Enhancement Mode Power MOSFET

DESCRIPTION

The HM25P03K uses advanced trench technology to provide excellent $R_{DS(ON)}$, low gate charge and operation with gate voltages as low as 4.5V.



Schematic diagram



Marking and pin assignment



TO-252-2L top view

GENERAL FEATURES

- $V_{DS} = -30V, I_D = -25A$
- $R_{DS(ON)} < 35m\Omega @ V_{GS}=-4.5V$
- $R_{DS(ON)} < 20m\Omega @ V_{GS}=-10V$
- High Power and current handing capability
- Lead free product is acquired
- Surface Mount Package

Application

- Battery Switch
- Load switch
- Power management

Package Marking And Ordering Information

| Device Marking | Device | Device Package | Reel Size | Tape width | Quantity |
|----------------|----------|----------------|-----------|------------|------------|
| HM25P03K | HM25P03K | TO-252-2L | Ø330mm | 12mm | 2500 units |

Absolute Maximum Ratings (TA=25°C unless otherwise noted)

| Parameter | Symbol | Limit | Unit |
|--|----------------|------------|------|
| Drain-Source Voltage | V_{DS} | -30 | V |
| Gate-Source Voltage | V_{GS} | ± 20 | V |
| Drain Current-Continuous | I_D | -25 | A |
| Drain Current-Pulsed (Note 1) | I_{DM} | -75 | A |
| Maximum Power Dissipation | P_D | 50 | W |
| Operating Junction and Storage Temperature Range | T_J, T_{STG} | -55 To 150 | °C |

Thermal Characteristic

| | | | |
|--|-----------------|----|------|
| Thermal Resistance, Junction-to-Ambient (Note 2) | $R_{\theta JA}$ | 40 | °C/W |
|--|-----------------|----|------|

Electrical Characteristics (TA=25°C unless otherwise noted)

| Parameter | Symbol | Condition | Min | Typ | Max | Unit |
|--------------------------------|------------|----------------------------|-----|-----|-----|------|
| Off Characteristics | | | | | | |
| Drain-Source Breakdown Voltage | BV_{DSS} | $V_{GS}=0V, I_D=-250\mu A$ | -30 | -33 | - | V |

| | | | | | | |
|---|---------------------|---|----|------|------|----|
| Zero Gate Voltage Drain Current | I _{DSS} | V _{DS} =-30V, V _{GS} =0V | - | - | -1 | μA |
| Gate-Body Leakage Current | I _{GSS} | V _{GS} =±20V, V _{DS} =0V | - | - | ±100 | nA |
| On Characteristics (Note 3) | | | | | | |
| Gate Threshold Voltage | V _{GS(th)} | V _{DS} =V _{GS} , I _D =-250μA | -1 | -1.5 | -3 | V |
| Drain-Source On-State Resistance | R _{DS(ON)} | V _{GS} =-10V, I _D =-10A | - | 15 | 20 | mΩ |
| | | V _{GS} =-4.5V, I _D =-7.0A | - | 21 | 35 | mΩ |
| Forward Transconductance | g _{FS} | V _{DS} =-15V, I _D =-9.1A | 10 | - | - | S |
| Dynamic Characteristics (Note4) | | | | | | |
| Input Capacitance | C _{iss} | V _{DS} =-15V, V _{GS} =0V, F=1.0MHz | - | 1600 | - | PF |
| Output Capacitance | C _{oss} | | - | 350 | - | PF |
| Reverse Transfer Capacitance | C _{rss} | | - | 300 | - | PF |
| Switching Characteristics (Note 4) | | | | | | |
| Turn-on Delay Time | t _{d(on)} | V _{DD} =-15V, ID=-1A, V _{GS} =-10V, R _{GEN} =6Ω | - | 10 | - | nS |
| Turn-on Rise Time | t _r | | - | 15 | - | nS |
| Turn-Off Delay Time | t _{d(off)} | | - | 110 | - | nS |
| Turn-Off Fall Time | t _f | | - | 70 | - | nS |
| Total Gate Charge | Q _g | V _{DS} =-15V, I _D =-9.1A V _{GS} =-10V | - | 30 | - | nC |
| Gate-Source Charge | Q _{gs} | | - | 5.5 | - | nC |
| Gate-Drain Charge | Q _{gd} | | - | 8 | - | nC |
| Drain-Source Diode Characteristics | | | | | | |
| Diode Forward Voltage (Note 3) | V _{SD} | V _{GS} =0V, I _S =-2.1A | - | - | -1.2 | V |

Notes:

1. Repetitive Rating: Pulse width limited by maximum junction temperature.
2. Surface Mounted on FR4 Board, t ≤ 10 sec.
3. Pulse Test: Pulse Width ≤ 300μs, Duty Cycle ≤ 2%.
4. Guaranteed by design, not subject to production

TYPICAL ELECTRICAL AND THERMAL CHARACTERISTICS

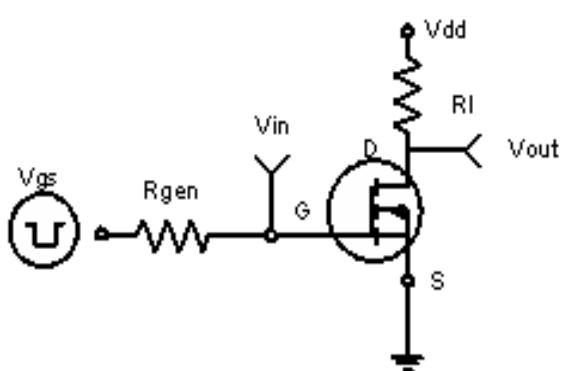


Figure 1:Switching Test Circuit

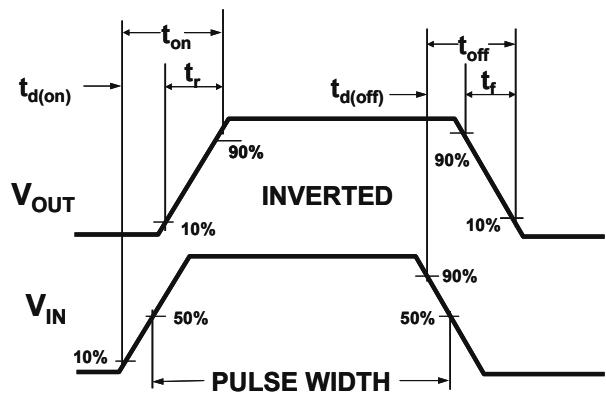


Figure 2:Switching Waveforms

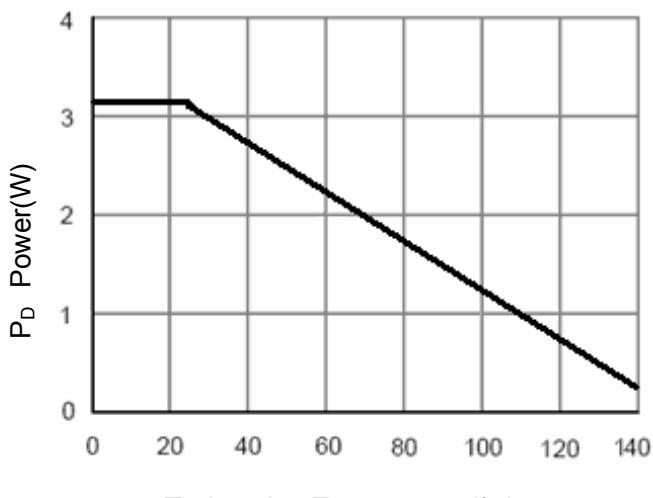


Figure 3 Power Dissipation

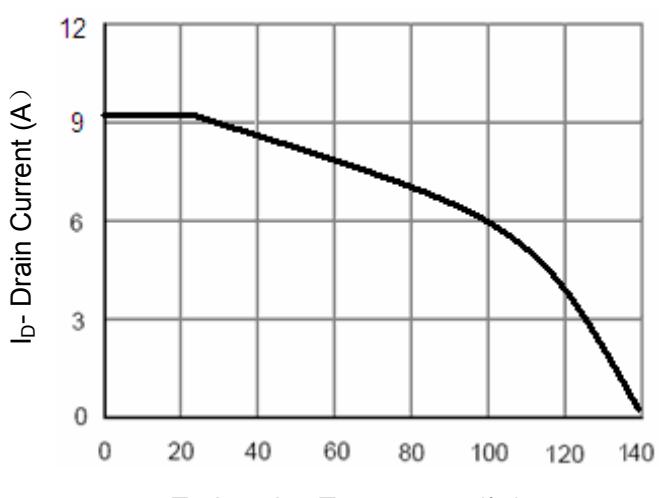


Figure 4 Drain Current

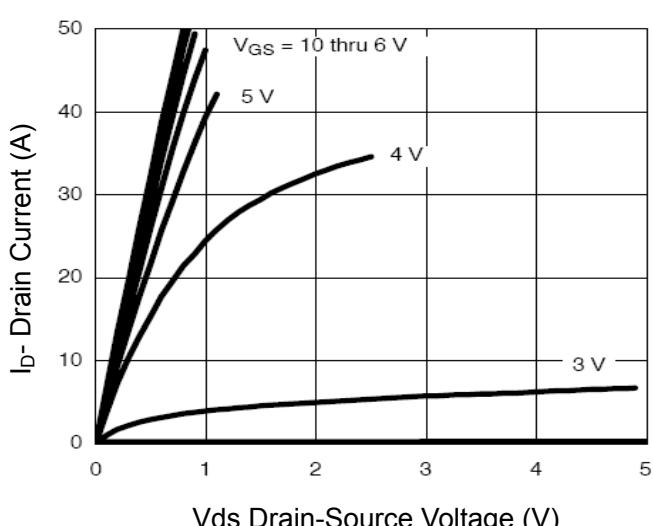


Figure 5 Output CHARACTERISTICS

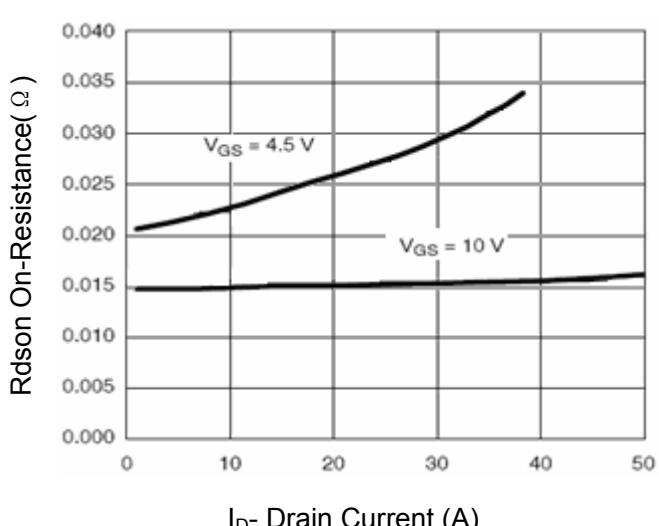


Figure 6 Drain-Source On-Resistance

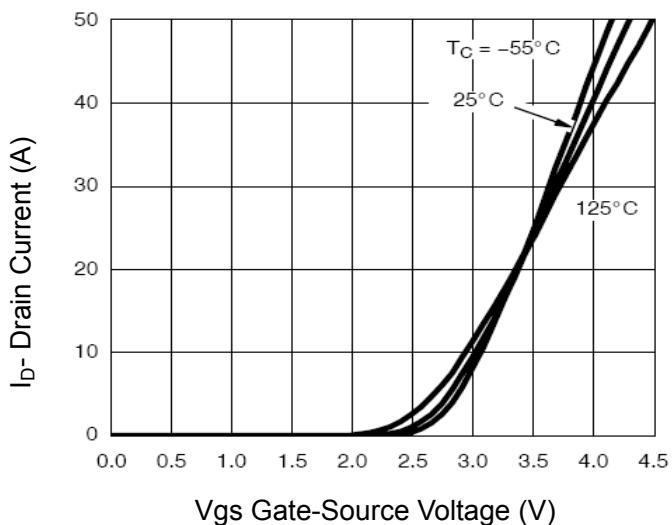


Figure 7 Transfer Characteristics

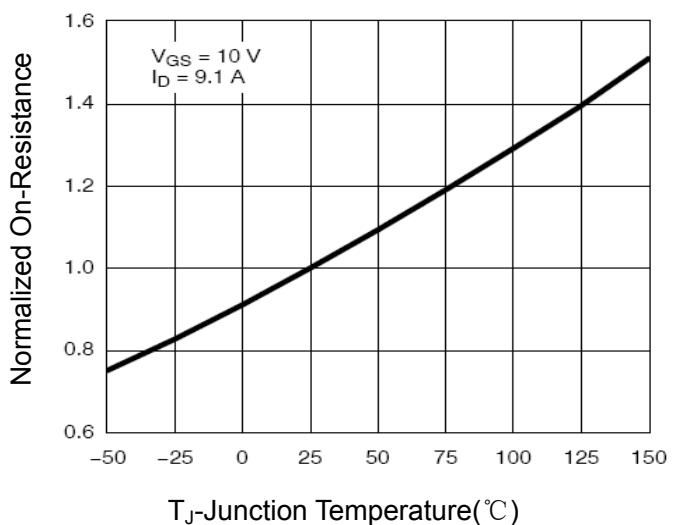


Figure 8 Drain-Source On-Resistance

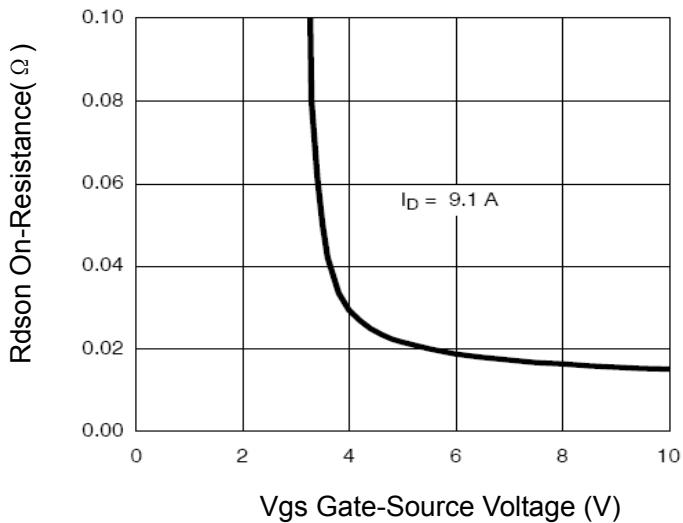


Figure 9 R_{DSON} vs V_{GS}

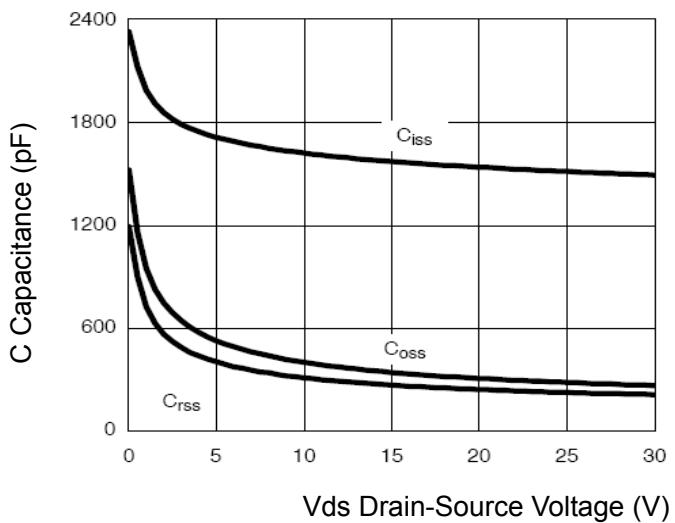


Figure 10 Capacitance vs V_{DS}

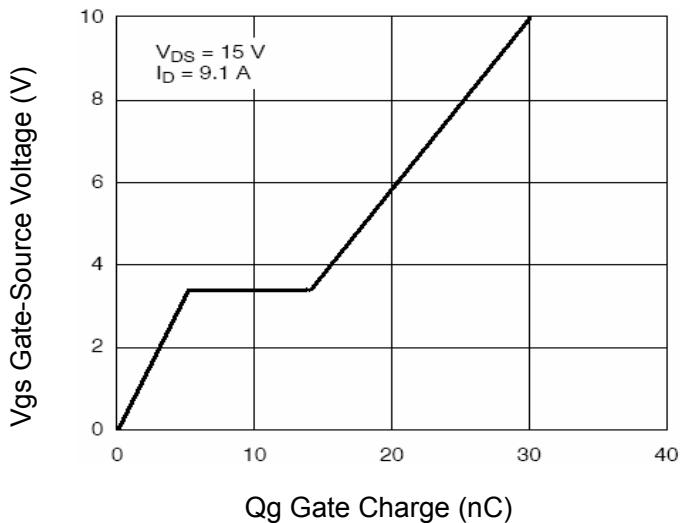


Figure 11 Gate Charge

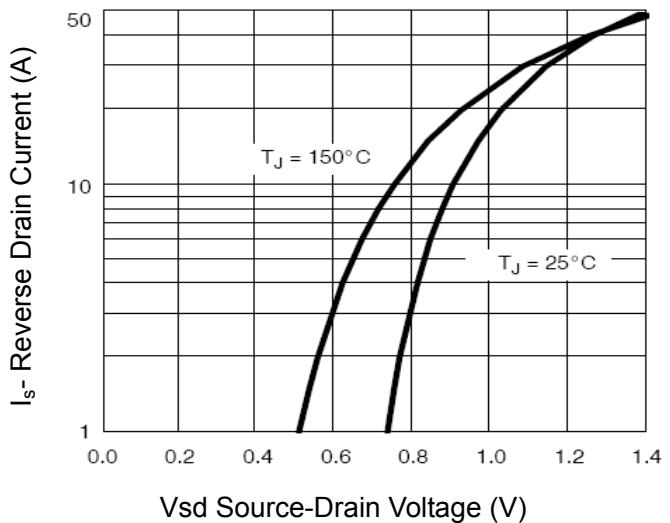


Figure 12 Source-Drain Diode Forward

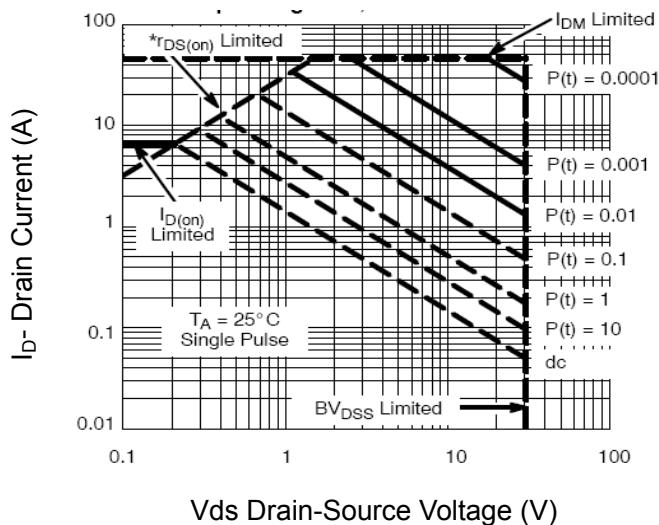


Figure 13 Safe Operation Area

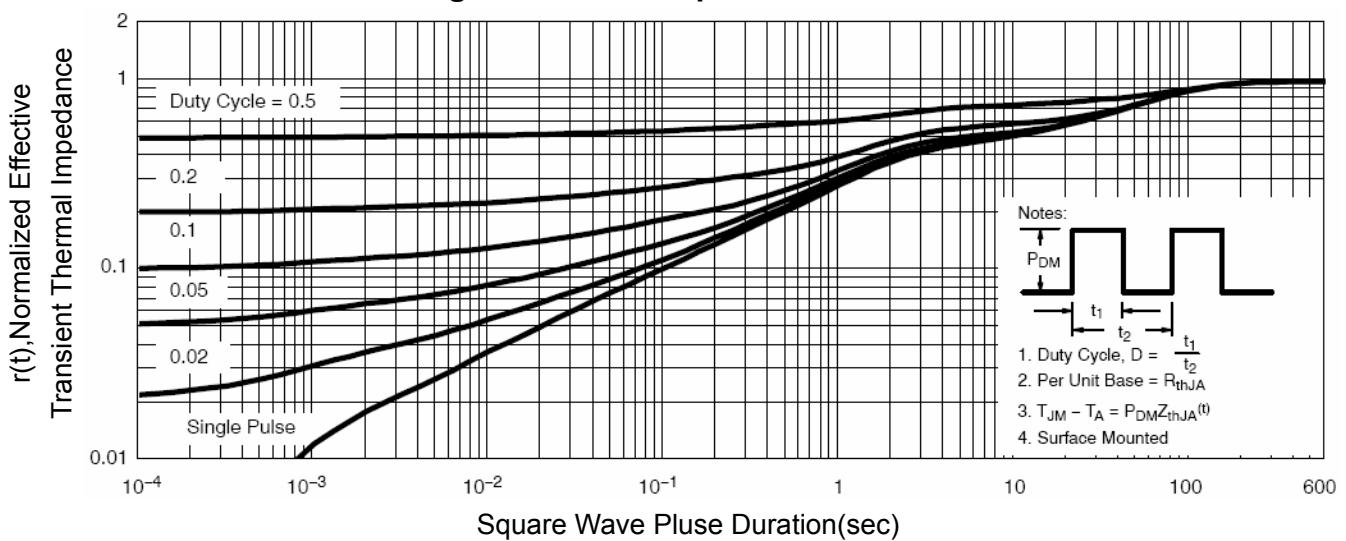
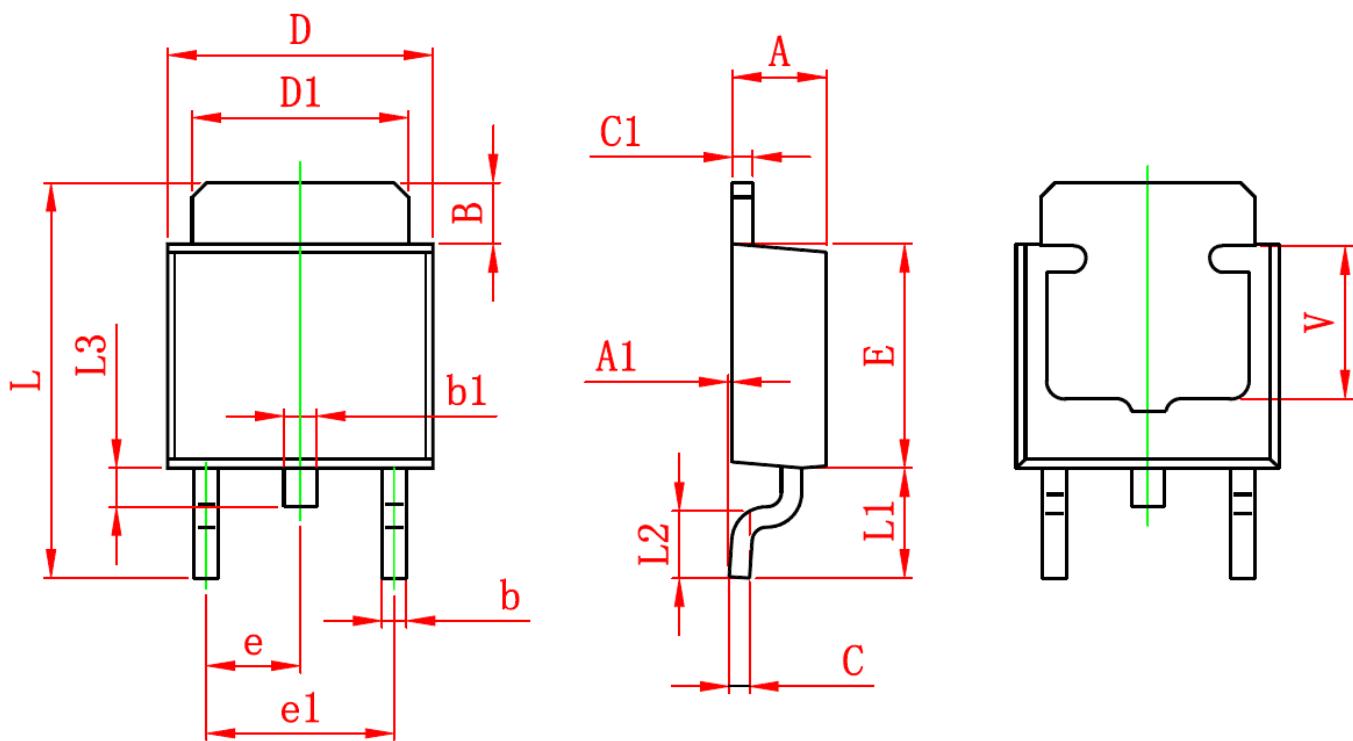


Figure 14 Normalized Maximum Transient Thermal Impedance

TO-252-2L PACKAGE OUTLINE DIMENSIONS



| Symbol | Dimensions In Millimeters | | Dimensions In Inches | |
|--------|---------------------------|-------|----------------------|-------|
| | Min. | Max. | Min. | Max. |
| A | 2.200 | 2.400 | 0.087 | 0.094 |
| A1 | 0.000 | 0.127 | 0.000 | 0.005 |
| B | 1.350 | 1.650 | 0.053 | 0.065 |
| b | 0.500 | 0.700 | 0.020 | 0.028 |
| b1 | 0.700 | 0.900 | 0.028 | 0.035 |
| c | 0.430 | 0.580 | 0.017 | 0.023 |
| c1 | 0.430 | 0.580 | 0.017 | 0.023 |
| D | 6.350 | 6.650 | 0.250 | 0.262 |
| D1 | 5.200 | 5.400 | 0.205 | 0.213 |
| E | 5.400 | 5.700 | 0.213 | 0.224 |
| e | 2.300 TYP. | | 0.091 TYP. | |
| e1 | 4.500 | 4.700 | 0.177 | 0.185 |
| L | 9.500 | 9.900 | 0.374 | 0.390 |
| L1 | 2.550 | 2.900 | 0.100 | 0.114 |
| L2 | 1.400 | 1.780 | 0.055 | 0.070 |
| L3 | 0.600 | 0.900 | 0.024 | 0.035 |
| V | 3.800 REF. | | 0.150 REF. | |